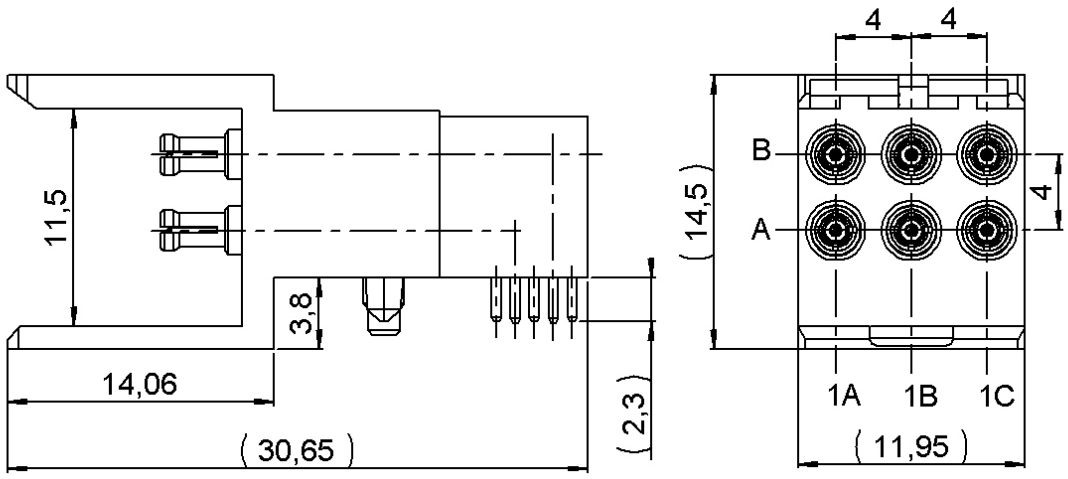
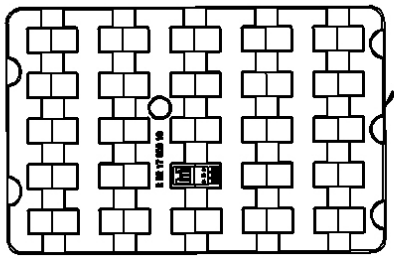
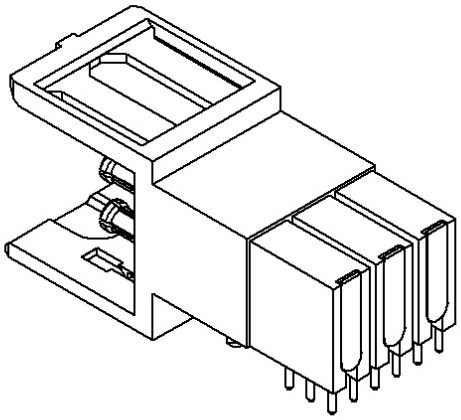
PAGE **1/4**	ISSUE **22-02-24B**	SERIES **MCC2**	PART NUMBER **R694251127**

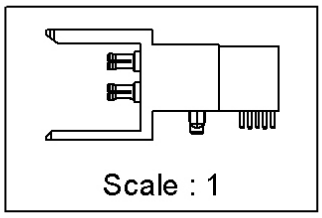
3 Coacx Position AB , 1A , 1B , 1C



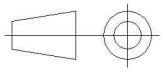


Connectors' packaging





All dimensions are in mm. Tolerances according ISO 2768 m-H



COMPONENTS	MATERIALS	PLATING (µm)
Body	**BRASS**	**NICKEL**
Center contact	**BERYLLIUM COPPER**	**NPGR**
Outer contact	**BRONZE**	**NPGR**
Insulator	**PEEK , ULTEM**	
Gasket		
Others parts	**LIQUID CRYSTAL POLYMER**	**NICKEL**
-	-	-
-	-	-

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PACKAGING

Standard	Unit	Other
25	**Contact us**	**Contact us**

ELECTRICAL CHARACTERISTICS

Impedance			**50**	Ω
Frequency			**0-6**	GHz
VSWR	**1.20***	**+**	**0,0000**	x F(GHz) Maxi
Insertion loss			**0.2**	√F(GHz) dB Maxi
RF leakage		- (	**-**	- F(GHz)) dB Maxi
Voltage rating			**500**	Veff Maxi
Dielectric withstanding voltage			**750**	Veff mini
Insulation resistance			**5000**	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	**6**	N mini
Axial force – Opposite end	**6**	N mini
Torque	**NA**	N.cm mini
Recommended torque		
Mating	**NA**	N.cm
Panel nut	**NA**	N.cm
Mating life	**500**	Cycles mini
Nominal Weight (Add +15% for max weight)	**7,4900**	g

ENVIRONMENTAL

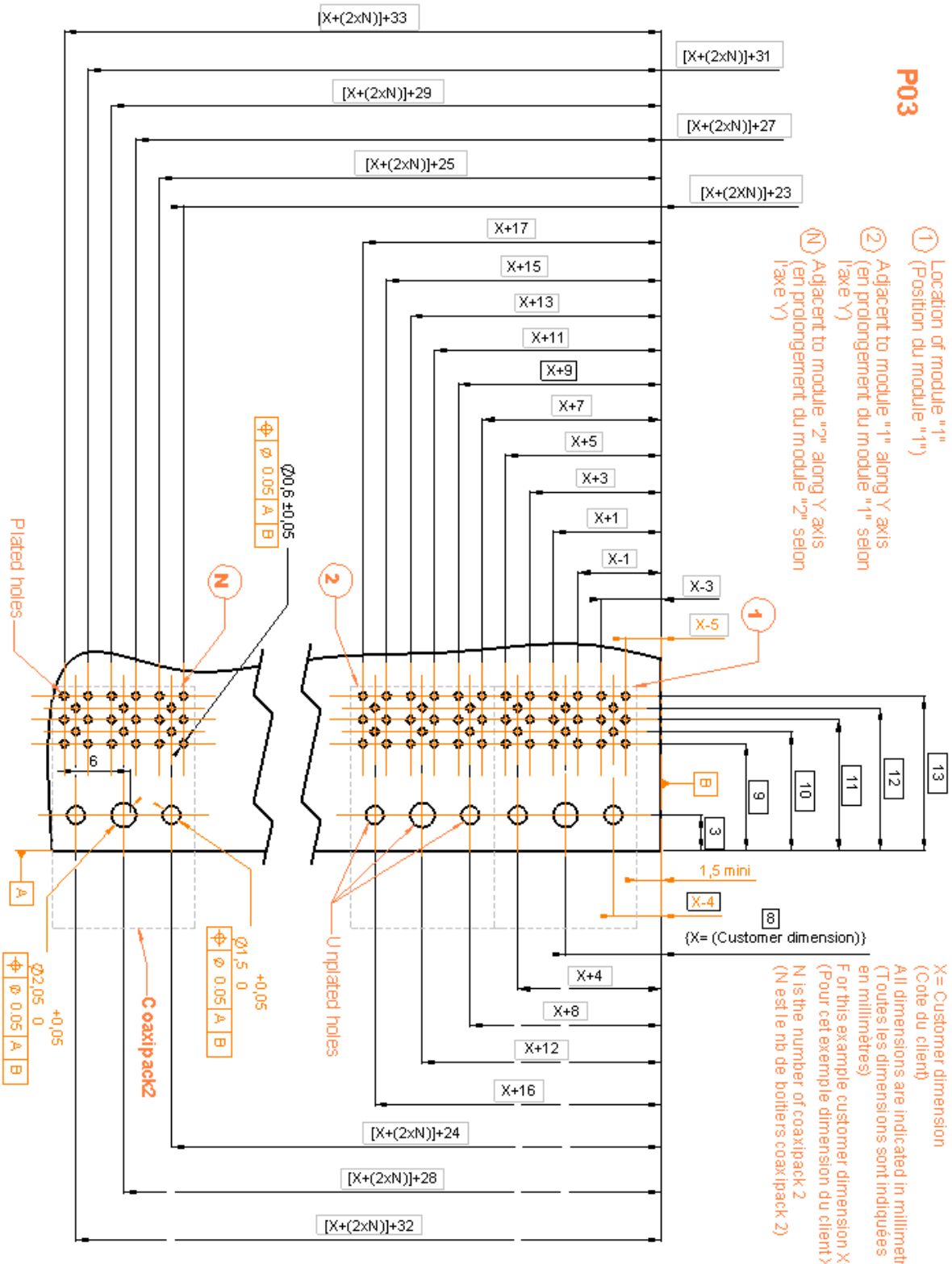
Operating temperature	**-25/+125**	°C
Hermetic seal	**NA**	Atm.cm3/s
Panel leakage	**NA**	

SPECIFICATION

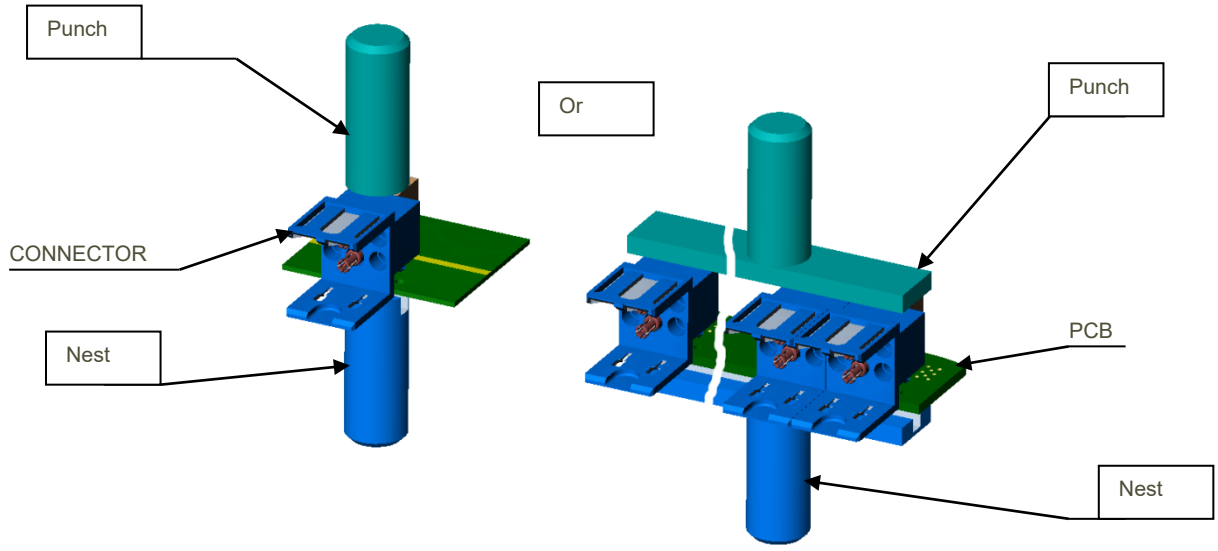
OTHER CHARACTERISTICS

Assembly instruction:

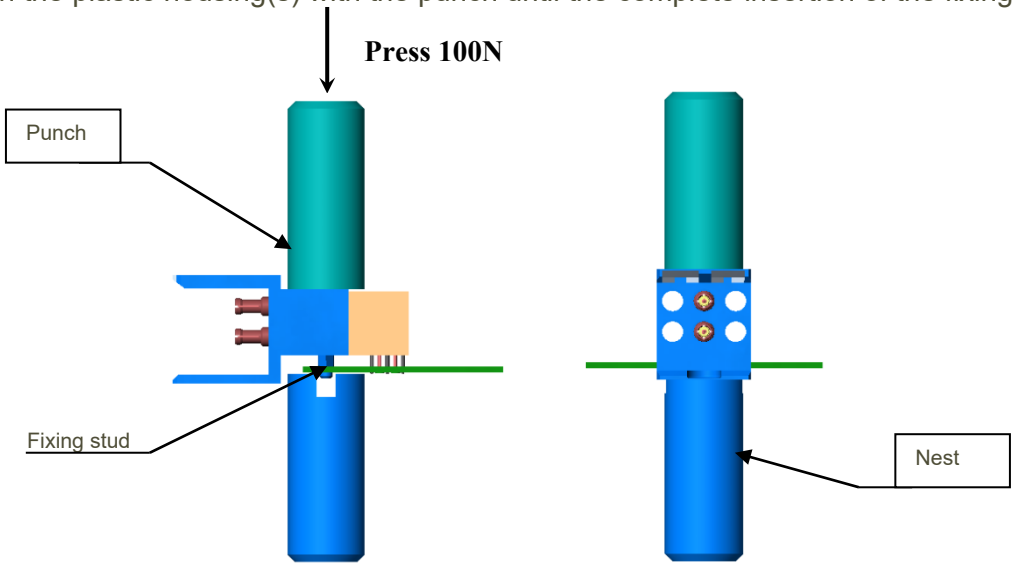
Others:
Optimised 0-3GHz



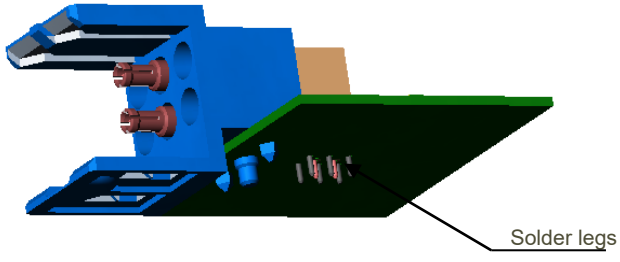
- Place the coax connector on the PCB



- Place correctly the PCB between the punch and the nest of the press.
- In case of multiple housing configuration , use a punch and a nest large enough to cover all the housings.
- Press on the plastic housing(s) with the punch until the complete insertion of the fixing stud into the PCB.



- Solder the legs on board



Radiall do not recommend to use more than 3 modules on the same motherboard and can't be held liable of any connection defect when more than 3 modules are implemented on the board